WHAT IS CLAIMED IS:

1. An etching agent for copper comprising an aqueous solution containing potassium hydrogen peroxomonosulfate.

2. An etching agent for copper according to Claim 1, wherein said aqueous solution contains acetic acid.

3. An etching agent for copper according to Claim 1, wherein the concentration of said potassium hydrogen peroxomonosulfate falls within a range of 0.08 to 2.0 mol/l.

4. An etching agent for a laminated film of a titanium film and a copper film comprising an aqueous solution containing potassium hydrogen peroxomonosulfate and hydrofluoric acid.

5. An etching agent for a laminated film of a molybdenum film and a copper film comprising an aqueous solution containing potassium hydrogen peroxomonosulfate, phosphoric acid and nitric acid.

6. An etching agent for a laminated film of a chromium film and a copper film comprising an aqueous solution containing potassium hydrogen peroxomonosulfate and hydrochloric acid.

Sub A2

7. An etching agent for a laminated film of a titanium film and a copper film comprising an aqueous solution containing a peroxomonosulfate salt, hydrofluoric acid, and hydrochloric acid or a chloride.

Sub B1

8. An etching agent for a laminated film of a titanium film and a copper film comprising an aqueous solution containing a peroxosulfate salt and a fluoride.

9. An etching agent for a laminated film of a titanium film and a copper film according to Claim 7, wherein said peroxosulfate salt comprises any one or more compounds selected from $KHSO_5$, $NaHSO_5$, $K_2S_2O_8$, $Na_2S_2O_8$ and $(NH_4)_2S_2O_8$.

Sub A3

10. An etching agent for a laminated film of a titanium film and a copper film according to Claim 7, wherein said chloride comprises an alkali metal chloride or ammonium chloride.

11. An etching agent for a laminated film of a titanium film and a copper film according to Claim 8, wherein said peroxosulfate salt comprises any one or more compounds selected from $KHSO_5$, $NaHSO_5$, $K_2S_2O_8$, $Na_2S_2O_8$ and $(NH_4)_2S_2O_8$.

12. An etching agent for a laminated film of a titanium film and a copper film according to Claim 8, wherein said fluoride

comprises an alkali metal fluoride or ammonium fluoride.

13. A method for manufacturing an electronic device substrate comprising the steps of: depositing a copper film on the substrate; forming a given pattern on the surface of the copper film; and etching the copper film using an etching agent comprising an aqueous solution containing potassium hydrogen peroxomonosulfate to form a copper wiring with a given pattern.

Sub A3 Cont

14. A method for manufacturing an electronic device substrate comprising the steps of: forming a mask with a given pattern on the surface of a laminated film prepared by sequentially depositing a titanium or titanium alloy film and a copper film on a substrate; and etching the laminated film comprising the titanium or titanium alloy film and the copper film using either an ethcing agent comprising an aqueous solution containing potassium hydrogen peroxomonosulfate and hydrofluoric aid, an etching agent comprising an aqueous solution containing a peroxosulfate salt and hydrochloric acid or a chloride, or an etching agent comprising an aqueous solution containing a peroxosulfate salt and a fluoride to form a laminated wiring with the given pattern.

15. An electronic device comprising an electronic device substrate prepared by a manufacturing method comprising the

steps of: depositing a copper film on a substrate; forming a mask with a given pattern on the copper film; and etching the copper film using an etching agent comprising an aqueous solution containing potassium hydrogen peroxomonosulfate to form a copper wiring with a given pattern.

16. An electronic device comprising an electronic device substrate manufactured by a manufacturing method comprising the steps of: forming a mask with a given pattern on a laminated film prepared by sequentially depositing a titanium or titanium alloy film and a copper film on a substrate; and etching the laminated film of the titanium or titanium alloy film and the copper film using either an etching agent comprising an aqueous solution containing potassium hydrogen peroxomonosulfate and hydrofluoric acid, an etching agent comprising an aqueous solution containing a peroxosulfate salt, hydrofluoric acid, and hydrochloric acid or a chloride, or an etching agent comprising an aqueous solution containing a peroxosulfate salt and a fluoride to from a laminated wiring with the given pattern.